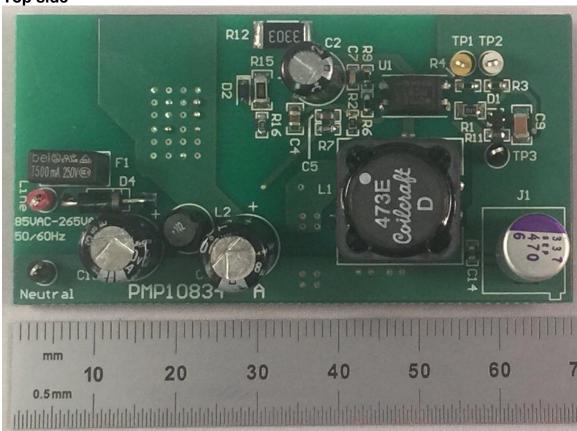


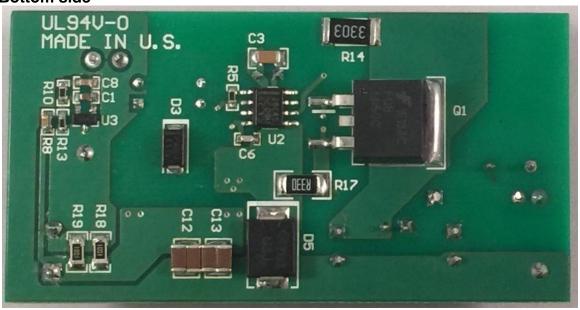
1 Photo

The photographs below show the PMP10834 Rev A assembly. This circuit was built on a PMP10834 Rev A PCB.

Top side



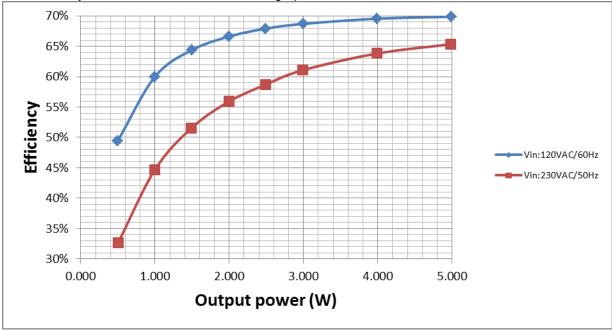
Bottom side





2 Converter Efficiency





V_{in} =120 V_{AC} /60HZ

| Vin(ac) | lin(A) | Pin(W) | Vout(V) | Iout(A) | Pout(W) | Eff. (%) |
|---------|---------|--------|---------|---------|---------|----------|
| 120.13 | 0.15404 | 7.143 | 4.990 | 1.00 | 4.990 | 69.86% |
| 120.20 | 0.12794 | 5.741 | 4.990 | 0.80 | 3.992 | 69.53% |
| 120.01 | 0.10192 | 4.366 | 4.990 | 0.60 | 2.999 | 68.69% |
| 120.03 | 0.08838 | 3.667 | 4.990 | 0.50 | 2.490 | 67.90% |
| 120.04 | 0.07562 | 3.004 | 4.990 | 0.40 | 2.001 | 66.61% |
| 120.06 | 0.06258 | 2.325 | 4.990 | 0.30 | 1.497 | 64.39% |
| 120.07 | 0.04858 | 1.664 | 4.990 | 0.20 | 0.998 | 59.98% |
| 120.08 | 0.03089 | 1.009 | 4.990 | 0.10 | 0.499 | 49.45% |
| 120.09 | 0.02117 | 0.666 | 4.990 | 0.05 | 0.235 | 35.21% |
| 120.09 | 0.01003 | 0.286 | 4.990 | 0.00 | 0.000 | 0.00% |

PMP10834 Rev A Test Results



V_{in} =230 V_{AC} /50Hz

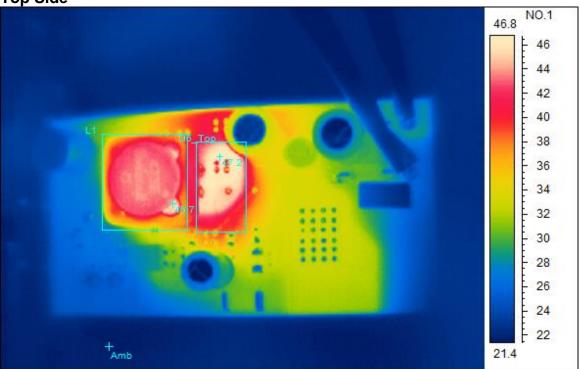
| Vin(ac) | lin(A) | Pin(W) | Vo1(V) | Io1(A) | Pout(W) | Eff. (%) |
|---------|---------|--------|--------|--------|---------|----------|
| 230.00 | 0.10347 | 7.630 | 4.980 | 1.00 | 4.985 | 65.33% |
| 230.00 | 0.08907 | 6.255 | 4.990 | 0.80 | 3.992 | 63.82% |
| 230.00 | 0.07421 | 4.895 | 4.990 | 0.60 | 2.989 | 61.06% |
| 230.00 | 0.06681 | 4.242 | 4.990 | 0.50 | 2.490 | 58.70% |
| 230.10 | 0.05829 | 3.570 | 4.990 | 0.40 | 1.996 | 55.91% |
| 230.10 | 0.04841 | 2.894 | 4.990 | 0.30 | 1.492 | 51.56% |
| 230.10 | 0.03831 | 2.234 | 4.990 | 0.20 | 0.998 | 44.67% |
| 230.10 | 0.02757 | 1.542 | 4.990 | 0.10 | 0.504 | 32.68% |
| 230.10 | 0.01839 | 0.999 | 4.990 | 0.05 | 0.254 | 25.47% |
| 230.10 | 0.00845 | 0.401 | 4.990 | 0.00 | 0.000 | 0.00% |



3 Thermal Images

The thermal images below show a top view and bottom view of the board under $120V_{AC}/60Hz$ and $230V_{AC}/50Hz$ input conditions. The ambient temperature was $20^{\circ}C$ with no forced air flow.

V_{in}=120V_{AC}/60Hz, V_{out}=5V/1A Top Side



| Spot analysis | Value |
|-----------------|--------|
| Amb Temperature | 21.6°C |
| Area analysis | Value |
| L1 Max | 45.7°C |
| D5_TopMax | 47.2°C |



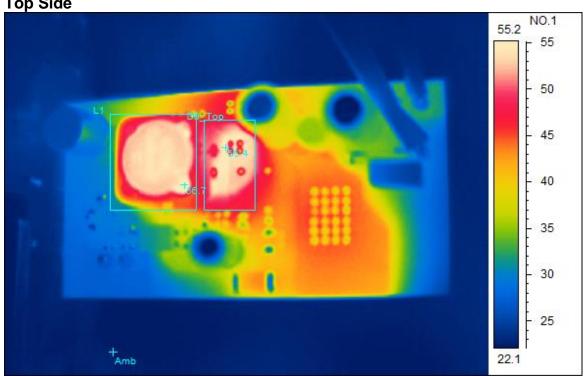
V_{in}=120V_{AC}/60Hz, V_{out}=5V/1A Bottom Side



| Spot analysis | Value |
|-----------------|--------|
| Amb Temperature | 24.7°C |
| Area analysis | Value |
| Q1Max | 39.7°C |
| D5 Max | 60.7°C |



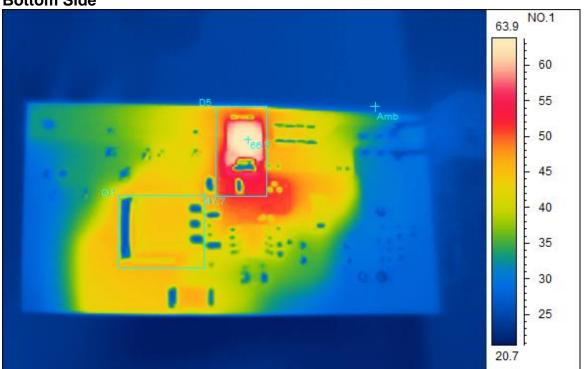
V_{in}=230V_{AC}/50Hz, V_{out}=5V/1A Top Side



| Spot analysis | Value |
|-----------------|--------|
| Amb Temperature | 22.7°C |
| Area analysis | Value |
| L1 Max | 56.7°C |
| D5_TopMax | 55.4°C |



V_{in} =230 V_{AC} /50Hz, V_{out} =5V/1A Bottom Side



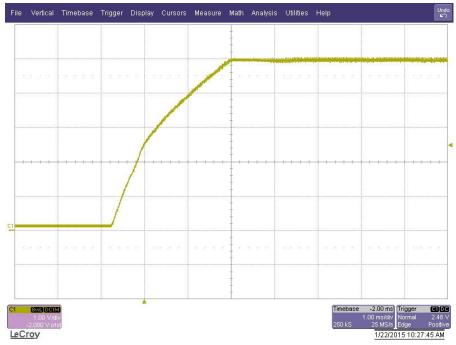
| Spot analysis | Value |
|-----------------|--------|
| Amb Temperature | 26.3°C |
| Area analysis | Value |
| Q1Max | 47.7°C |
| D5 Max | 66.7°C |



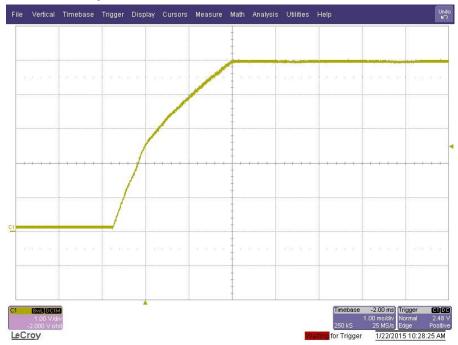
4 Startup Waveforms

The output voltages at startup with constant current load are shown in the images below.

4.1 Start Up @ 120V_{AC}/60Hz: 5V/1A.



4.2 Start Up @ 120VAC/60Hz: no load.

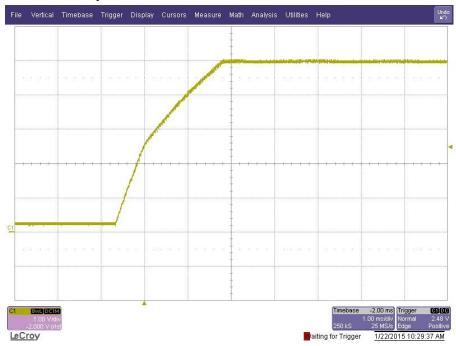




4.3 Start Up @ 230V_{AC}/50Hz: 5V/1A.



4.4 Start Up @ 230V_{AC}/50Hz: no load.

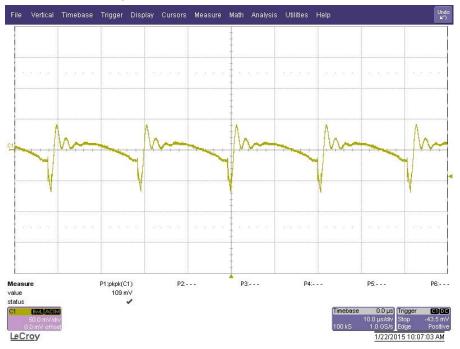




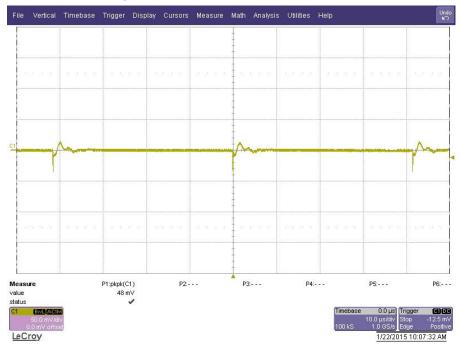
5 Output Ripple Voltages

The output ripple voltages are shown in the plots below.

5.1 $V_{in}=120V_{AC}/60Hz$: 5V/1A.



5.2 V_{in} =120 V_{AC} /60Hz: No load.





5.3 $V_{in}=230V_{AC}/50Hz$: 5V/1A.



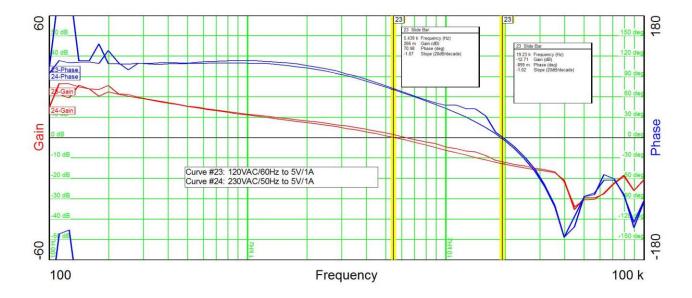
5.4 V_{in} =230 V_{AC} /50Hz: No load.





6 Frequency response

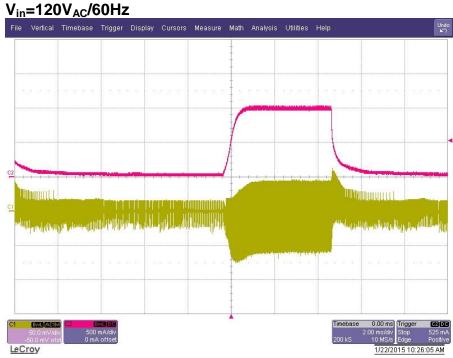
The frequency response is measured with 5V/1A output.





7 Load dynamic response

The load dynamic response is measured with 5V/1A output. Load step from 0.015A to 1A





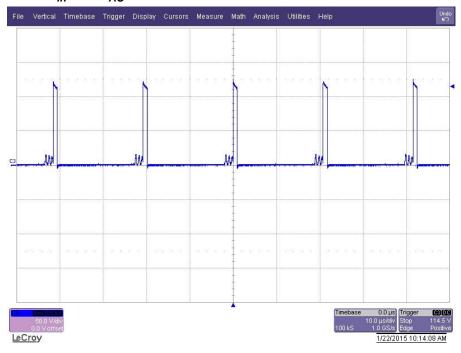




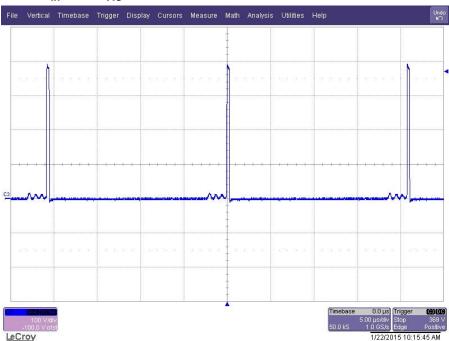
8 Switching Waveforms

The images below show key switching waveforms of PMP10834RevA. The waveforms are measured with 1A full load.

8.1 V_{in} = 90 V_{AC} /60Hz:



8.2 $V_{in}=264V_{AC}/50Hz$:



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